

[ABSTRACT]

[Invention Title]

CERAMIC CUTTING METHOD AND EQUIPMENT

5 The present invention relates to a ceramic cutting
method and equipment, which is provided with a
configuration comprising: a beam irradiation unit for
irradiating a beam of a wavelength that is absorbed by a
pattern formed on an upper surface of a ceramic and
10 partially absorbed by the ceramic; a coolant spraying unit
for spraying a coolant onto the ceramic irradiated with
the beam, wherein part or all of the pattern is removed by
heating and cooling the ceramic at the same time, and is
cut by reducing thermal damage by using the stress caused
15 by the recrystallization of an upper layer or all of the
ceramic or the stress generated by the thermal expansion
and contraction of the upper layer or all of the ceramic,
thereby recrystallizing the ceramic by heating and cooling
the ceramic at the same time, or cutting the ceramic by
20 heating until the ceramic melts, and cooling to apply
thermal stress to the inside of the ceramic, followed by
an additional separation process of a ceramic material
without loss.

25 [FIG. 1]